ABSTRACT

A chip size package in which an elastomer of low elasticity for damping and absorbing a stress, as might otherwise be concentrated on bump electrodes, is formed over the principal face of a semiconductor chip and in which wires connected with bonding pads are led out to the upper face of the elastomer through through holes formed in the elastomer and are connected at their one-end portions with the bump electrodes. On the other hand, the wires, as led out to the upper face of the elastomer are formed in a curved pattern so that the stress to be concentrated on the bump electrodes may be absorbed and damped by the extension and contraction of not only the elastomer but also the wires.